IN THE CLAIMS:

Please cancel claims 1-7 and 13-18 without prejudice or disclaimer.

Please amend claims 8-12 and 19 as follows:

Renumbered Claims 4/29/04

1. (Canceled)

2. (Canceled)

3. (Canceled)

4. (Canceled)

5. (Canceled)

6. (Canceled)

7. (Canceled)

8. (Currently Amended) An electrostatic chucking device manufacturing method including

a step in which a polyimide film which constitutes a first insulation layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm, a metal foil which constitutes an electrode layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm and a polyimide film which constitutes a second insulation layer are sequentially superposed,

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form an electrostatic chucking sheet which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer,

a step in which the electrostatic chucking sheet is superposed on a metal substrate by way of a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm, and

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form a laminated structure which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer on the metal substrate ~~An electrostatic chucking device manufacturing method according to claim 7~~,

wherein the polyimide film which constitutes the first insulation layer and the thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm are preliminarily integrally laminated to form a first laminated sheet, the polyimide film which constitutes the second insulation layer and the thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm are preliminarily integrally laminated to form a second laminated sheet, and a metal foil is inserted between respective adhesive films of the first laminated sheet and the second laminated sheet, and the first laminated sheet, the second laminated sheet and the metal foil are subjected to a low-temperature compression bonding processing under pressure at a heating temperature of 100 to 250°C so as to form the electrostatic chucking sheet.

6 ~~9~~. (Currently Amended) An electrostatic chucking device manufacturing method according to any one of ~~preceding~~ claims 1-5 ~~5-8, 10-12 and 19 to 8~~, wherein the metal substrate is made of an aluminum alloy metal substrate.

2 ~~10.~~ (Currently Amended) An electrostatic chucking device manufacturing method including

a step in which a polyimide film which constitutes a first insulation layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm, a metal foil which constitutes an electrode layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm and a polyimide film which constitutes a second insulation layer are sequentially superposed,

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form an electrostatic chucking sheet which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer,

a step in which the electrostatic chucking sheet is superposed on a metal substrate by way of a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm, and

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form a laminated structure which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer on the metal substrate ~~according to any one of preceding claims 5 to 8~~,

wherein the polyimide films which constitute the first insulation layer and the second insulation layer have a film thickness of 20 to 50 μm.

3 ~~11.~~ (Currently Amended) An electrostatic chucking device manufacturing method including

a step in which a polyimide film which constitutes a first insulation layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm, a metal foil which constitutes an electrode layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm and a polyimide film which constitutes a second insulation layer are sequentially superposed,

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form an electrostatic chucking sheet which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer,

a step in which the electrostatic chucking sheet is superposed on a metal substrate by way of a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm, and

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form a laminated structure which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer on the metal substrate ~~according to any one of preceding claims 5 to 8~~,

wherein the low-temperature compression bonding processing is performed under the compression condition of 2 to 5 MPa in the thicknesswise direction in the atmosphere.

12. (Currently Amended) An electrostatic chucking device manufacturing method including

a step in which a polyimide film which constitutes a first insulation layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm, a metal foil which constitutes an electrode layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm and a polyimide film which constitutes a second insulation layer are sequentially superposed,

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form an electrostatic chucking sheet which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer,

a step in which the electrostatic chucking sheet is superposed on a metal substrate by way of a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm, and

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form a laminated structure which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer on the metal substrate ~~according to any one of preceding claims 5 to 8~~,

wherein the low-temperature compression bonding processing is performed under the compression condition of 0.1 to 5 MPa in the thicknesswise direction in the reduced-pressure atmosphere of not more than 133 Pa.

13. (Canceled)

14. (Canceled)

15. (Canceled)

16. (Canceled)

17. (Canceled)

18. (Canceled)

~~19.~~ (Currently Amended) An electrostatic chucking device manufacturing method including

a step in which a polyimide film which constitutes a first insulation layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm, a metal foil which constitutes an electrode layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm and a polyimide film which constitutes a second insulation layer are sequentially superposed,

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form an electrostatic chucking sheet which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer,

a step in which the electrostatic chucking sheet is superposed on a metal substrate by way of a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm, and

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form a laminated structure which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer on the metal substrate ~~according to any one of claims 5 to 8~~,

wherein the polyimide films of the first and second insulation layers have a film thickness in a range of 20 μm and less than 50 μm.